

FORM PTO-1449 (Modified)

LIST OF PATENTS AND PUBLICATIONS FOR
APPLICANT'S INFORMATION DISCLOSURE
STATEMENT (Use several sheets if necessary)

Attorney Docket No.: A5031/T433000

Application No.: Unassigned

Applicant: SCOTT BRAD HERNER

Filing Date: Herewith

Group: Unassigned

10/07/01
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Reference Designation

U.S. PATENT DOCUMENTS

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Examiner Initial	Document No.	Date	Name	Class	Sub-class	Filing Date (If Appropriate)
TN AA	5,306,666	04/26/94	Izumi	437	192	
AB	5,328,722	07/12/94	Ghanayem, et al.	427	250	
AC	5,429,991	07/04/95	Iwasaki, et al.	437	192	
AD	5,599,639	02/04/97	Sansone, et al.	429	33	
TN AE	6,303,480 B1	10/16/01	Desai, et al.	438	584	
AF						
AG						
AH						
AI						
AJ						

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub-class	Translation (Yes/No)
AK						
AL						

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

TN AM	HERNER, S.B., et al., "Homogeneous Tungsten Chemical Vapor Deposition on Silane Pretreated Titanium Nitride," Electrochemical and Solid-State Letters, 2 (8) 1999, pp. 398-400.
TN AN	MCINERNEY, E.J., et al., "Silane Reduced Chemical Vapor Deposition Tungsten as a Nucleating Step in Blanket W," J. Vac. Sci. Technol. B 11 (3), May/Jun 1993, pp. 734-743.
TN AO	RAMANATH, G., et al., "Gas-Phase Transport of WF ₆ through Annular Nanopipes in TiN During Chemical Vapor Deposition of W on TiN/Ti/SiO ₂ Structures for Integrated Circuit Fabrication," Appl. Phys. Lett. 69 (21), 18 November 1996, pp. 3179-3181.
TN AP	NANDA, Arun K., et al., "Characterization of the Nucleation and Growth Process of CVD-W on TiN Substrates," Mat. Res. Soc. Symp. Proc. Vol. 382, 1995 Materials Research Society, pp. 401-406.
TN AQ	HERNER, S.B., et al., "Volcano Reactions in Oxide Vias Between Tungsten CVD and Bias Sputtered TiN/Ti Films," Journal of the Electrochemical Society, 147 (5) 2000, pp. 1982-1987.
AR	
AS	

EXAMINER

DATE CONSIDERED

1/9/02

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.